

**Application Number Information**

Application Number: 10/590210

**Assignments**

Filing or 371(c) Date: 00/00/0000 eDan

Effective Date: 08/22/2006

Application Received: 08/22/2006

Patent Number:

Issue Date: 00/00/0000

Date of Abandonment: 00/00/0000

Attorney Docket Number: 59404US004

Status: 19 /APPLICATION UNDERGOING PREEXAM PROCESSING Status Date: 08/28/2006

Confirmation Number: 4407

Examiner Number: 00000 /

Group Art Unit: 1732

**IFW Madras**

Class/Subclass: 264/.

Lost Case: NO

Interference Number:

Unmatched Petition: NO

L&R Code: Secrecy Code:1

Third Level Review: NO

Secrecy Order: NO

Oral Hearing: NO

Title of Invention: **METHOD OF MOLDING FOR MICRONEEDLE ARRAYS**

Bar Code	PALM Location	Location Date	Charge to Loc	Charge to Name	Employee Name	Location
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